

Automated Fluid Dispensing with Advanced Process Control

Fluidmove

Fluid Dispensing Software

**India Dispensione Software

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The Quantum® Q-6800 Series offers uncompromising quality, speed, flexibility, and value with batch and inline dispensing for automotive, PCBA, and various electronic assembly applications.

The system includes a calibration station and advanced closed-loop process controls such as a fluid weight scale, patented Mass Flow Control (MFC), and Calibrated Process Jetting (CPJ). These controls ensure the right amount of material is dispensed for each part from the beginning to the end of the production run. Dynamic Dispense Control (DDC) provides precise valve control for more accurate placement of dots and lines.

With over 30 years of precision fluid dispensing experience, our worldwide engineering, applications development, and technical service network provide expert support from initial process development through full-scale production.

Features and Benefits

- Supports CSP, BGA, and board-level underfill.
- Supports surface mount adhesive, corner and edge bonding, dam and fill, potting and encapsulation, conductive epoxy, and case assembly applications.
- Large dispense area (423 x 458 mm) ideal for dual-valve dispensing and a range of substrate sizes.
- Range-finding laser height sensor enables fast, noncontact dispense height measurement.
- A digital vision system with enhanced vision software enables quick finding and teaching of fiducials even when targets vary in size, contrast, or rotation.
- Patented CPJ process control automatically compensates for changes in fluid viscosity for higher yield.



Specifications

Dispense Area (X-Y) (1)	423 x 458 mm (16.7 x 18.0 in.), single applicator with offsets for vision and height sense; tooling size dependent.	
Board Handling (1)	Max. board/carrier thickness	12 mm (0.5 in.)
	Min. board/carrier width	25 mm (0.98 in.)
Not applicable for the Batch configuration.	Max. board/carrier width	Single lane: 520 mm (20.4 in.) Dual lane: up to 220 mm (8.6 in.)
	Min. board/carrier length	25 mm (0.98 in.)
	Max. board/carrier length	One station: 600 mm (23.6 in.) Three stations: 320 mm (12.6 in.)
Computer	Laptop	
Software	Fluidmove* fluid dispensing software	
Facilities Requirements	System footprint	1100 x 1241 mm (43.3 x 48.8 in.)
	System weight (2)	435-490 kg (960-1080 lbs.)
Standards Compliance	SEMI-S2 SEMI-S8 SMEMA CE	
Optional Features	 Dual applicator support Dual-lane configuration Fids-on-the-Fly software for high-speed fiducial capture Pre and post-queue stations SECS/GEM interface 	

⁽¹⁾ Contact the factory regarding other travel distances and board/carrier size compatibility.



 $[\]ensuremath{\text{(2)}}\ \mbox{System weight varies depending on the configuration.}$

System Packages

Nordson Electronics Solutions builds the future of electronics reliability all across the globe. We're proud of the decades of service and solutions we've provided to enhance electronics reliability. No matter where you are, you've likely manufactured or purchased a product made reliable with our equipment. The Quantum® Q-6800 Series is an ideal fluid dispensing platform for automotive, PCBA, and various electronic assembly applications.

Explore the Quantum Q-6800 system packages. Continue to see how we support the future.

For more information, contact us at info-electronics@nordson.com.

Essential	Single-valve dispensing.	An economically efficient and reliable single-valve dispensing solution designed for automotive, PCBA, and various electronic assembly applications.
Productivity	Dual-action and pre-queue dispensing.	Accelerate throughput with dual-action dispensing and pre-queue process capabilities. Dispense two materials to the same part with dual action to increase throughput by up to 25%.
Productivity Plus	Dual-action and pre and post-queue dispensing.	Dual-action dispensing of two materials accelerates throughput, while pre and post-queue processing reduces transport time for maximum productivity.

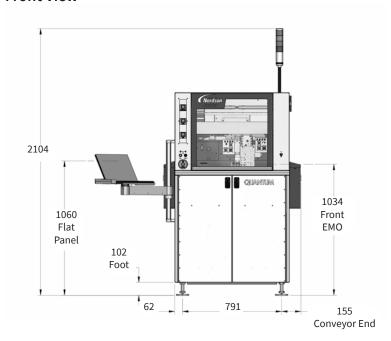
Recommended Options

Software Enabled	SECS/GEM CAD Import Software, Windows*
Conveyance and Tooling	Standard tooling Flexible impingement tooling Custom tooling (with approval)
Fluid Delivery	Magnetic low fluid sensor Capacitive low fluid sensor Needle heater
Power Kit	European power cord

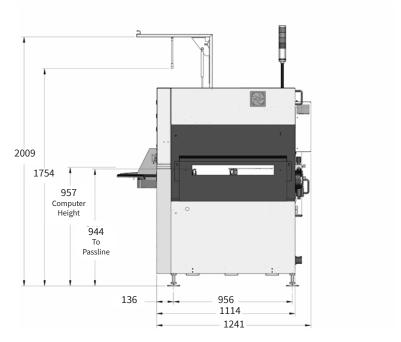


System Dimensions

Front View



Side View



Dimensions in millimeters.

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We have several global locations to serve you.

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